Special Issue

Recent Advances in Integrated Non-reciprocal Devices

Message from the Guest Editor

Non-reciprocal devices are ubiquitously used in modern communication, radar and sensing technologies. Traditionally, these non-reciprocal components are realized using ferrites. However, these ferrites-based non-reciprocal devices are bulky, expensive and require high deposition temperatures for fabrication, thereby making them incompatible with modern-day semiconductor fabrication processes. Recognizing the need for integrated non-reciprocal components and their potential to disrupt the technologies ranging from communication, radar, optics, medial and quantum computing. This Special Issue requests submissions pertaining to this research goal, in order to employ materials and/or techniques to integrate non-reciprocal components to semiconductor media. Topics of interest for this Special Issue include but are not limited to RF, millimeter wave and optical non-reciprocal devices based on time-modulation, non-linearity, active current/voltage transistors, and non-conventional material/fabrication processes that can be integrated with semiconductor.

Guest Editor

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